Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 7502 Switch Chassis (JD242C)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

3.1.1 Guidance of treatments to the product:

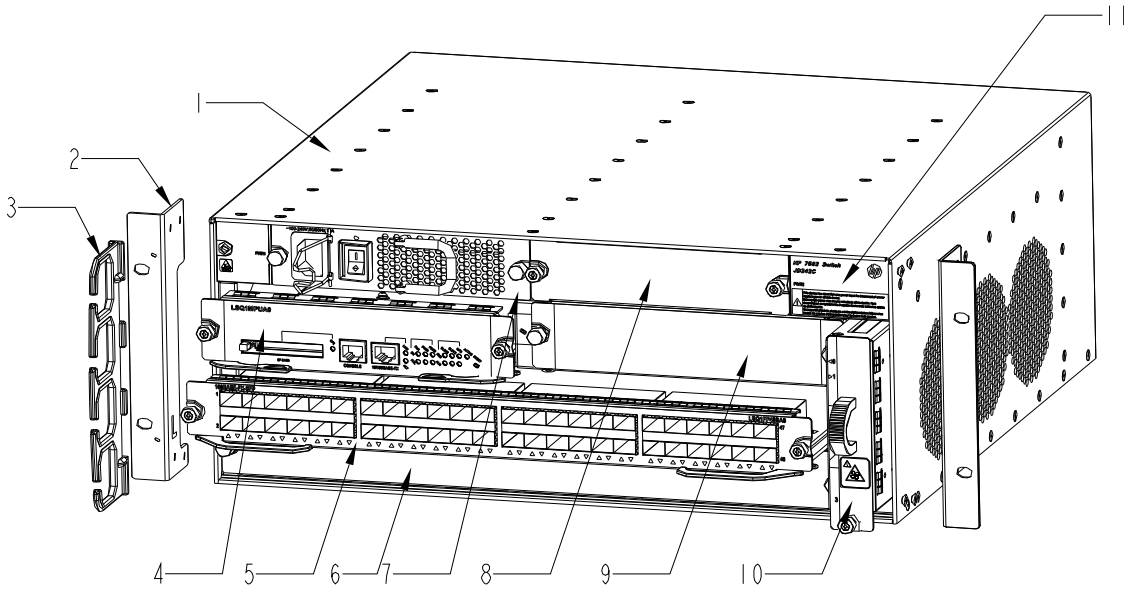

Figure 1 Front of HP 7502

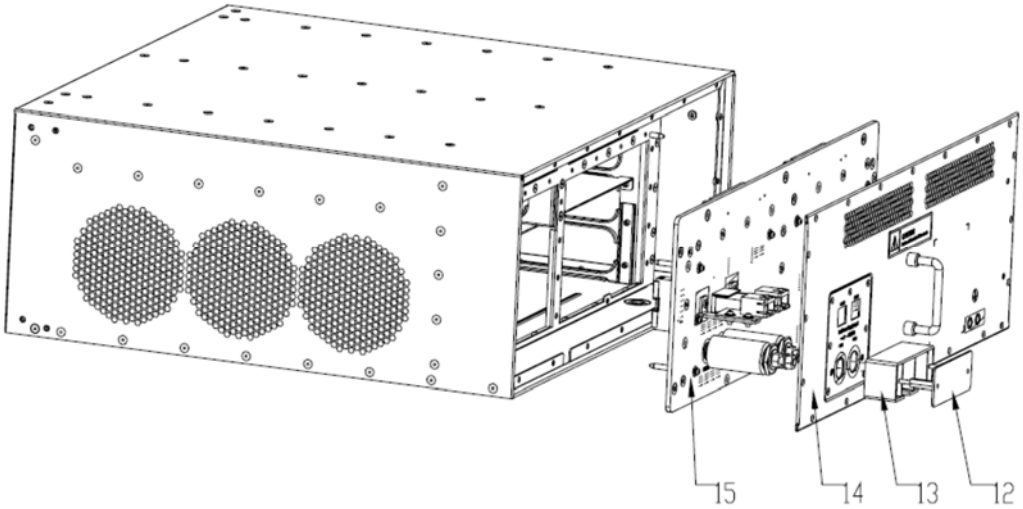

Figure 2 Rear of HP 7502

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2;
2. Unscrew the screws on cabling rack 3, and then remove cabling rack 3 from mounting angle 2;
3. Unscrew the screws on front panel 4, and then remove front panel 4;
4. Unscrew the screws on front panel 5, and then remove front panel 5;
5. Unscrew the screws on blank panel 6, and then remove blank panel 6;
6. Unscrew the screws on power supply module 7, and then remove power supply module 7;
7. Unscrew the screws on blank panel 8, and then remove blank panel 8;
8. Unscrew the screws on blank panel 9, and then remove blank panel 9;
9. Unscrew the screws on fan module 10, and then remove fan module 10;
10. Remove film 11;
11. Unscrew the screws on rear cover plate 11, and then remove rear cover plate 11;
12. Unscrew the screws on protection cover 12, and then remove protection cover 12;
13. Unscrew the screws on protection box 13, and then remove protection box 13;
14. Unscrew the screws on rear cover plate 14, and then remove rear cover plate 14;
15. Unscrew the screws on PCB 15, and then remove PCB 15;
16. Remove all of the labels;
17. Remove all of shielding fingers.

3.1.2 Guidance of treatments to module 4:

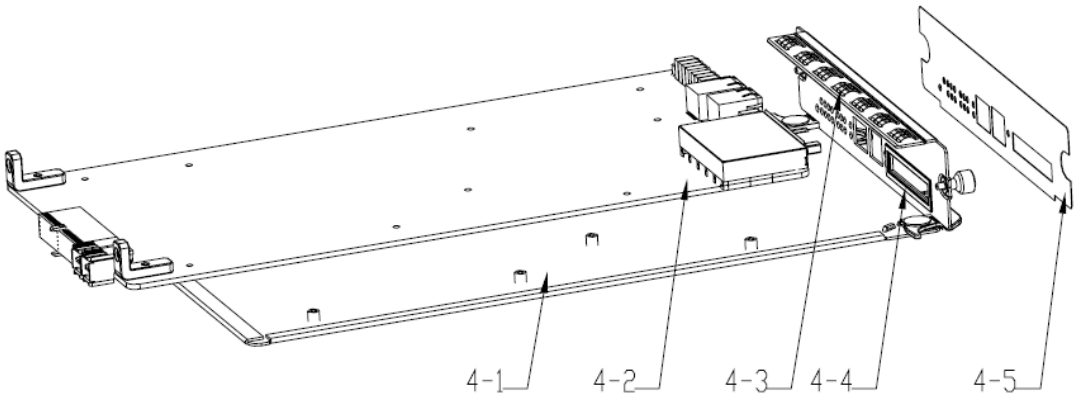

Figure 3 Treatments to module 4

1. Unscrew the screws on PCB 4-2, and then remove PCB 4-2;
2. Remove shielding finger 4-3 from front panel 4-1;
3. Remove conductive foam 4-4 from front panel 4-1;

4. Remove film 4-5 from front panel 4-1.

3.1.3 Guidance of treatments to module 5:

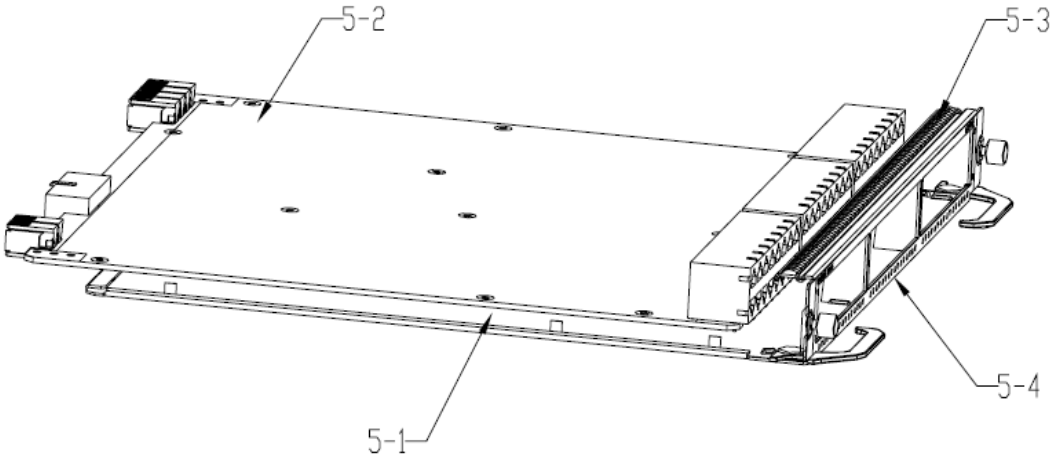

Figure 4 Treatments to module 5

1. Unscrew the screws on PCB 5-2, and then remove PCB 5-2;
2. Remove shielding finger 5-3 from front panel 5-1;
3. Remove film 5-4 from front panel 5-1.

3.1.4 Guidance of treatments to blank panel 6:

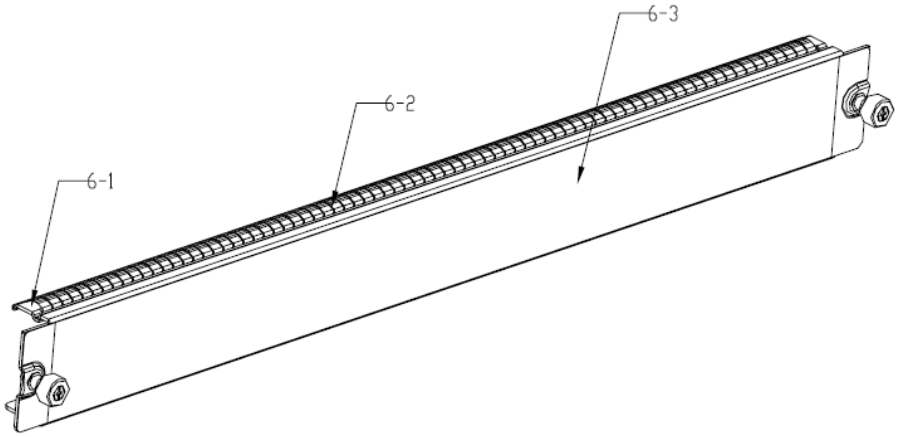

Figure 5 Treatments to blank panel 6

1. Remove shielding finger 6-2 from blank panel 6-1;
2. Remove film 6-3 from blank panel 6-1.

3.1.5 Guidance of treatments to blank panel 8

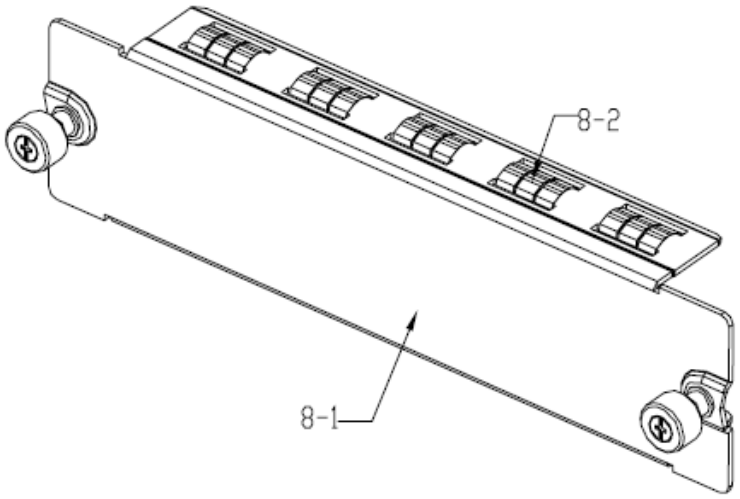

Figure 6 Treatments to blank panel 8

1. Remove shielding finger 8-2 from blank panel 8-1.

3.1.6 Guidance of treatments to blank panel 9

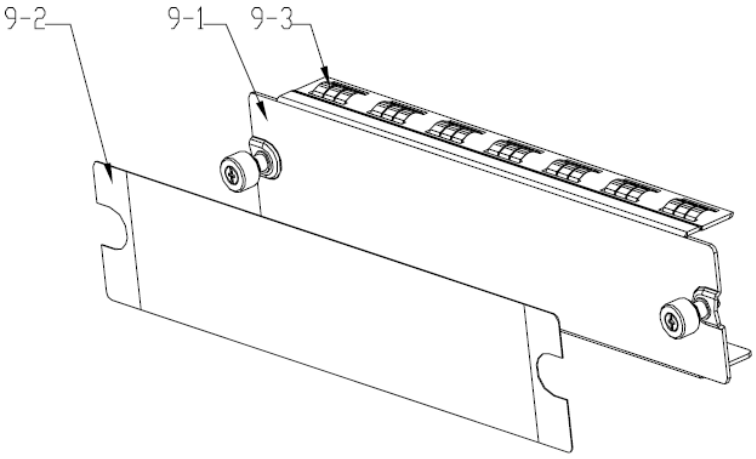

Figure 7 Treatments to blank panel 9

1. Remove film 9-2 from blank panel 9-1;
2. Remove shielding finger 9-3 from blank panel 9-1.

3.1.7 Guidance of treatments to fan module 10

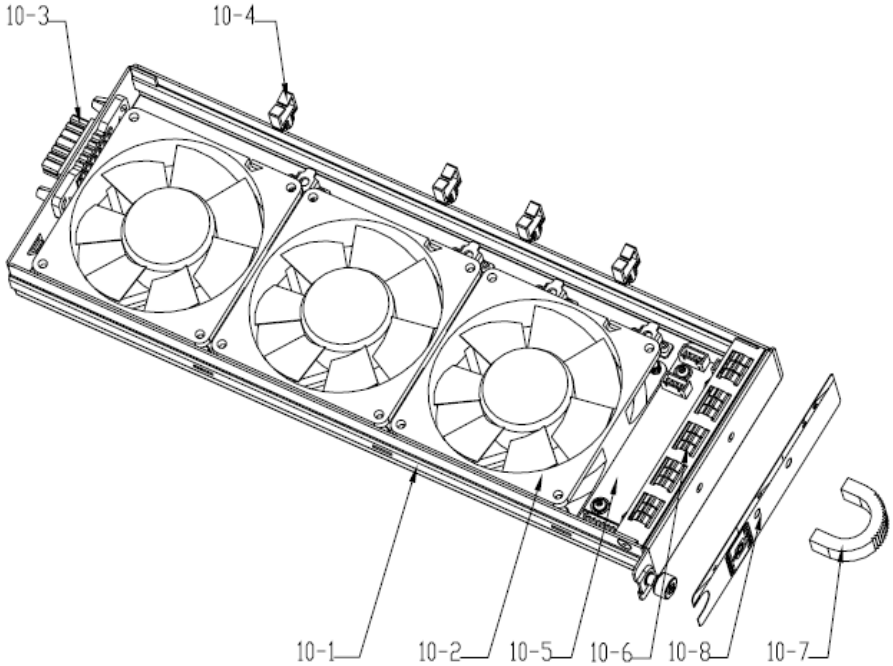

Figure 8 Treatments to fan module 10

1. Remove the three fans 10-2 from fan frame 10-1;
2. Remove plug 10-3 from fan frame 10-1;
3. Remove the four wire mounts 10-4 from fan frame 10-1;
4. Unscrew the screws on PCB 10-5, and then remove PCB 10-5;
5. Remove shielding finger 10-6 from fan frame 10-1;
6. Unscrew the screws on handle 10-7, and then remove handle 10-7;
7. Remove film 10-8 from fan frame 10-1.

3.2 Material of the facility built

Facility	Components	Material	Weight (g)	Weight percentage	Selective treatment for materials and components	Details
	1	Fe	10411	50.46%		Fe recycling
	2	Fe	278	1.34%		Fe recycling
	3	ABS	22	0.10%		Pla recycling
4						
	4-1	AL	767	3.71%		Al recycling
	4-2	Complex PWB	519	2.51%	The surface of PCB is greater than 10 square centimeters	
5						
	5-1	Fe	1487	7.20%		Fe recycling
	5-2	Complex PWB	1000	4.84%	The surface of PCB is greater than 10 square centimeters	
6						
	6-1	Fe	303	1.46%		Fe recycling
	7	Complex PWB+Fe	2600	12.6%	1. Containing brominated flame retardants ; 2. The surface of PCB is greater than 10 square centimeters; 3. Electrolyte	Fe recycling

					capacitor height is more than 25 mm.	
8						
	8-1	Fe	122	0.59%		Fe recycling
9						
	9-1	Fe	156	0.75%		Fe recycling
10						
	10-1	Fe	431	2.08%		Fe recycling
	10-2	Pla	98*3	1.42%		Pla recycling
	10-5	Complex PWB	35	0.16%	The surface of PCB is greater than 10 square centimeters	
	14	Fe	798	3.86%		Fe recycling
	15	Complex PWB	725	3.51%	The surface of PCB is greater than 10 square centimeters	
cables	0404A068 04042967 0404A07J 04041104	Cu, Pla	682	3.30%	1. Containing brominated flame retardants 2. 04041104 is external cables	Cu、Pla recycling

4. Revised record

Date	Version	Author	Modify content
2015.06.26	V0	Liao Wenqing	Initial version